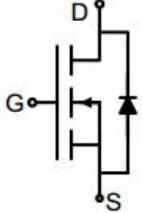
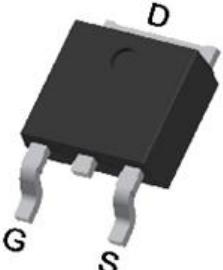


N-Channel Enhancement Mode Power MOSFET

| | |
|---|--|
| <p>Description</p> <p>The 18N20 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge. It can be used in a wide variety of applications.</p> <p>General Features</p> <ul style="list-style-type: none"> ● V_{DS} 200V ● I_D (at $V_{GS} = 10V$) 18A ● $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 190mΩ ● 100% Avalanche Tested ● RoHS Compliant <p>Application</p> <ul style="list-style-type: none"> ● Power switch ● DC/DC converters |  <p>Schematic diagram</p>  <p>TO-252</p> |
|---|--|

| Ordering Information | | | |
|-----------------------------|----------------|----------------|------------------|
| Device | Package | Marking | Packaging |
| 18N20 | TO-252 | 18N20 | 2500pcs/Reel |

| Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted | | | |
|---|----------------|--------------|-------------|
| Parameter | Symbol | Value | Unit |
| Drain-Source Voltage | V_{DS} | 200 | V |
| Continuous Drain Current | I_D | 18 | A |
| Pulsed Drain Current (note1) | I_{DM} | 72 | A |
| Gate-Source Voltage | V_{GS} | ± 20 | V |
| Power Dissipation | P_D | 65.8 | W |
| Single pulse avalanche energy (note2) | E_{AS} | 90 | mJ |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | -55 To 150 | °C |

| Thermal Resistance | | | |
|---|---------------|--------------|-------------|
| Parameter | Symbol | Value | Unit |
| Thermal Resistance, Junction-to-Ambient | R_{thJA} | 50 | °C/W |
| Maximum Junction-to-Case | R_{thJC} | 1.9 | °C/W |

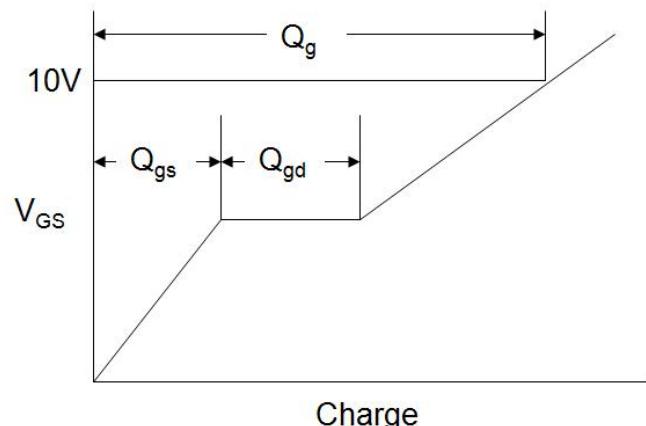
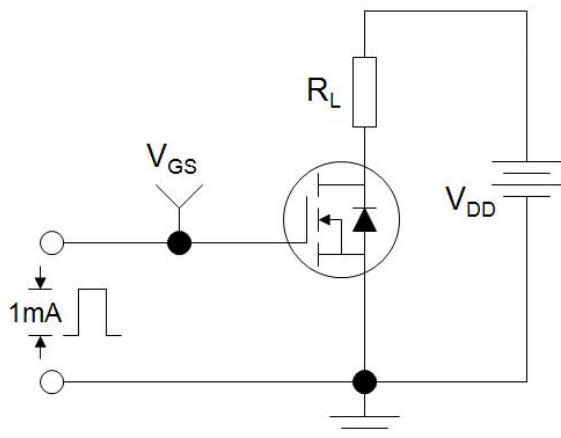
Specifications $T_J = 25^\circ\text{C}$, unless otherwise noted

| Parameter | Symbol | Test Conditions | Value | | | Unit |
|--|-----------------------------|---|-------|------|-----------|------------------|
| | | | Min. | Typ. | Max. | |
| Static Parameters | | | | | | |
| Drain-Source Breakdown Voltage | $V_{(\text{BR})\text{DSS}}$ | $V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$ | 200 | -- | -- | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{\text{DS}} = 200\text{V}, V_{\text{GS}} = 0\text{V}$ | -- | -- | 1 | μA |
| Gate-Source Leakage | I_{GSS} | $V_{\text{GS}} = \pm 20\text{V}$ | -- | -- | ± 100 | nA |
| Gate-Source Threshold Voltage | $V_{\text{GS}(\text{th})}$ | $V_{\text{DS}} = V_{\text{GS}}, I_D = 250\mu\text{A}$ | 1.0 | 1.4 | 3.0 | V |
| Drain-Source On-Resistance | $R_{\text{DS}(\text{on})}$ | $V_{\text{GS}} = 10\text{V}, I_D = 9\text{A}$ | -- | 129 | 190 | $\text{m}\Omega$ |
| Forward Transconductance | g_{FS} | $V_{\text{GS}} = 5\text{V}, I_D = 9\text{A}$ | -- | 8 | -- | S |
| Dynamic Parameters | | | | | | |
| Input Capacitance | C_{iss} | $V_{\text{GS}} = 0\text{V}, V_{\text{DS}} = 100\text{V}, f = 1.0\text{MHz}$ | -- | 847 | -- | pF |
| Output Capacitance | C_{oss} | | -- | 68 | -- | |
| Reverse Transfer Capacitance | C_{rss} | | -- | 13 | -- | |
| Total Gate Charge | Q_g | $V_{\text{DD}} = 100\text{V}, I_D = 9\text{A}, V_{\text{GS}} = 10\text{V}$ | -- | 18 | -- | nC |
| Gate-Source Charge | Q_{gs} | | -- | 4 | -- | |
| Gate-Drain Charge | Q_{gd} | | -- | 5.3 | -- | |
| Turn-on Delay Time | $t_{\text{d}(\text{on})}$ | $V_{\text{DD}} = 100\text{V}, I_D = 9\text{A}, R_G = 5\Omega$ | -- | 42 | -- | ns |
| Turn-on Rise Time | t_r | | -- | 20.5 | -- | |
| Turn-off Delay Time | $t_{\text{d}(\text{off})}$ | | -- | 125 | -- | |
| Turn-off Fall Time | t_f | | -- | 6.5 | -- | |
| Drain-Source Body Diode Characteristics | | | | | | |
| Continuous Body Diode Current | I_S | $T_C = 25^\circ\text{C}$ | -- | -- | 18 | A |
| Body Diode Voltage | V_{SD} | $T_J = 25^\circ\text{C}, I_{\text{SD}} = 9\text{A}, V_{\text{GS}} = 0\text{V}$ | -- | -- | 1.2 | V |
| Reverse Recovery Charge | Q_{rr} | $I_F = 9\text{A}, V_{\text{GS}} = 0\text{V}$ $dI/dt = 100\text{A}/\mu\text{s}$ | -- | 1066 | -- | nC |
| Reverse Recovery Time | T_{rr} | | -- | 239 | -- | ns |

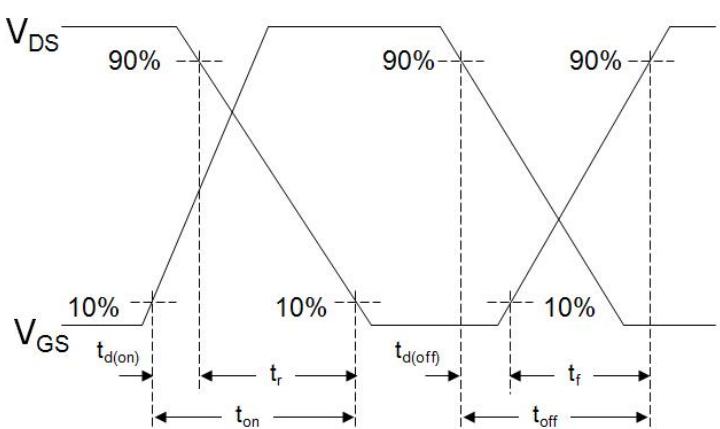
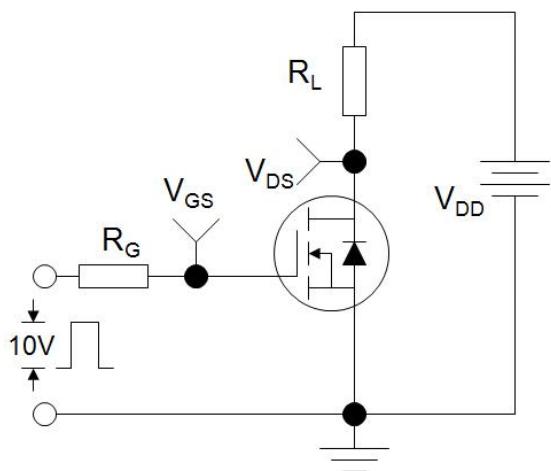
Notes

- Repetitive Rating: Pulse width limited by maximum junction temperature
- EAS condition : $T_J=25^\circ\text{C}$, $V_{\text{DD}}=50\text{V}$, $V_{\text{GS}}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$
- Identical low side and high side switch with identical R_G

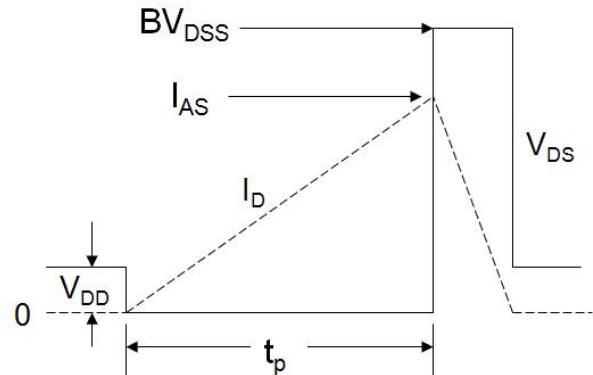
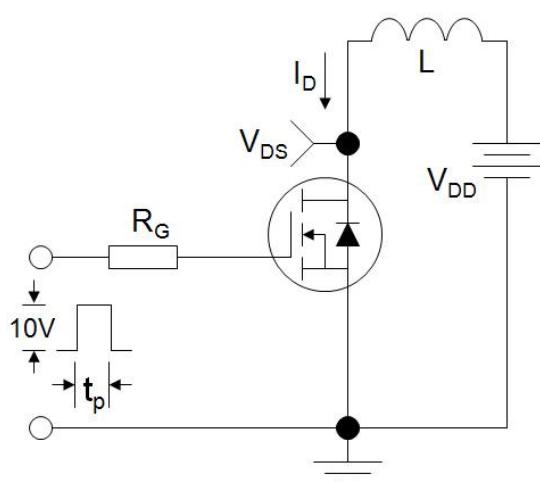
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics

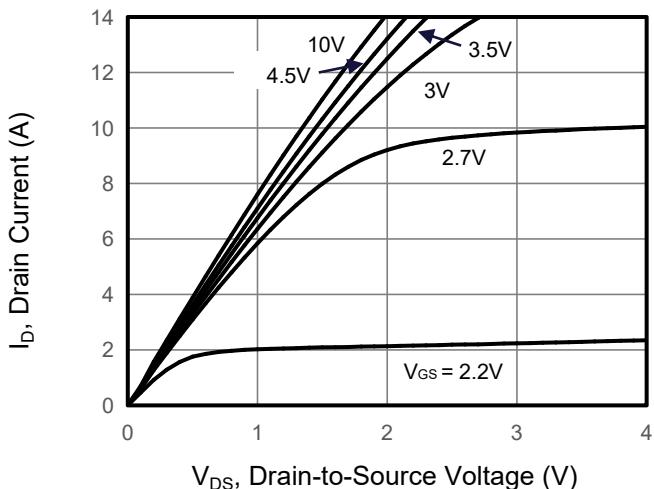


Figure 2. Transfer Characteristics

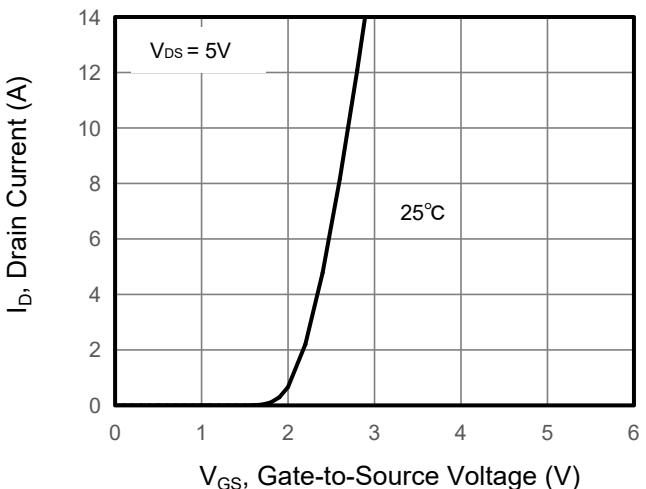


Figure 3. Drain Source On Resistance

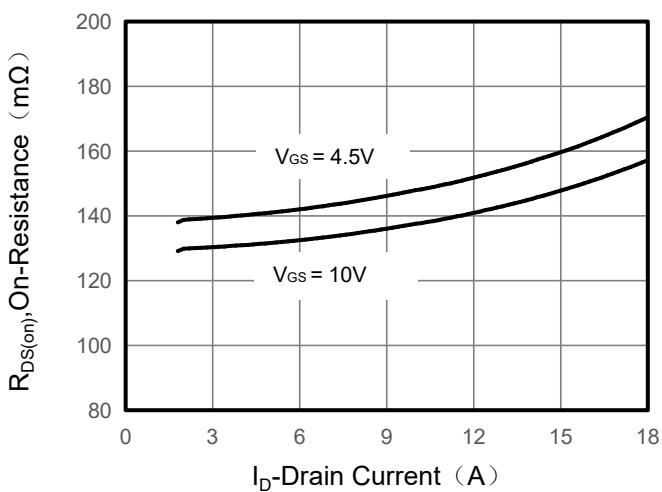


Figure 4. Gate Charge

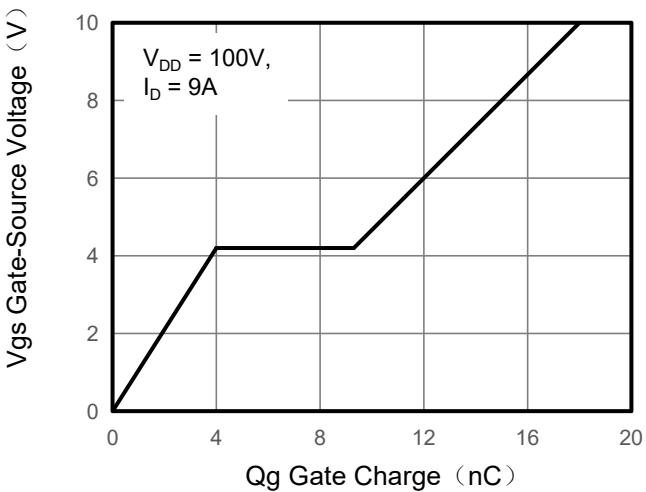


Figure 5. Capacitance

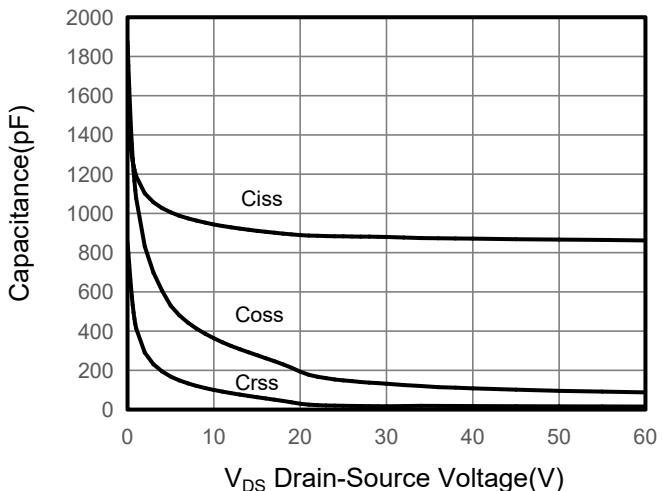
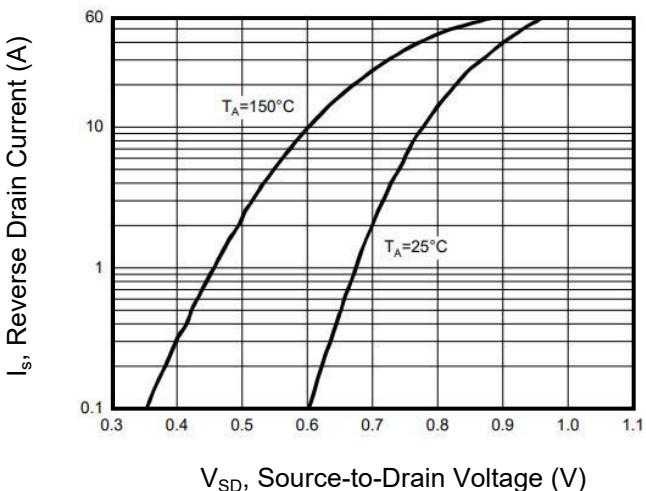


Figure 6. Source-Drain Diode Forward



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 7. Drain-Source On-Resistance

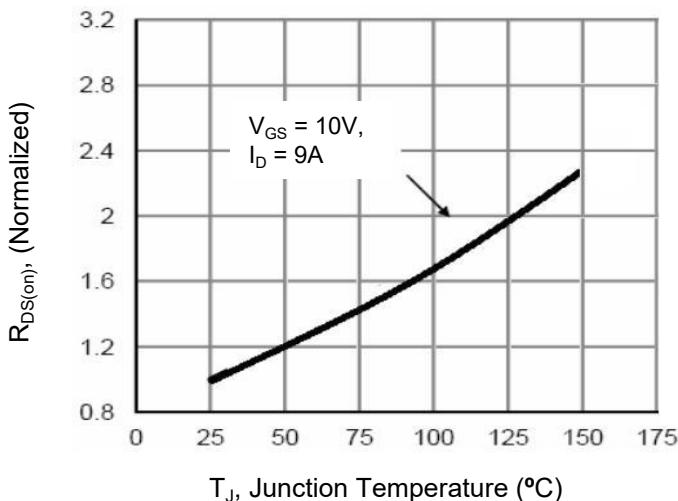


Figure 8. Safe Operation Area

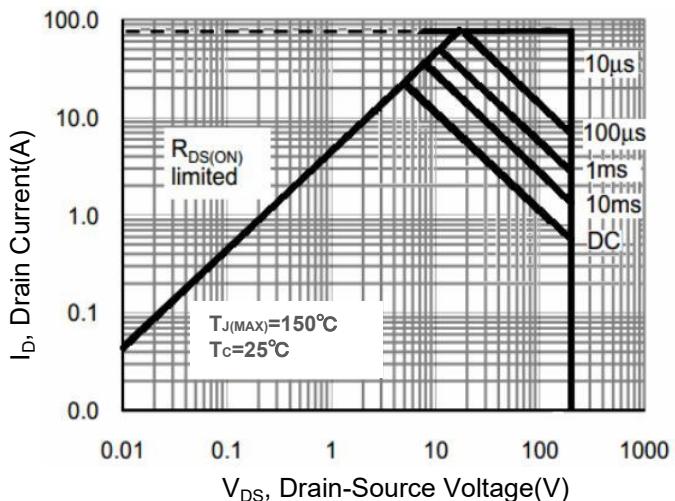
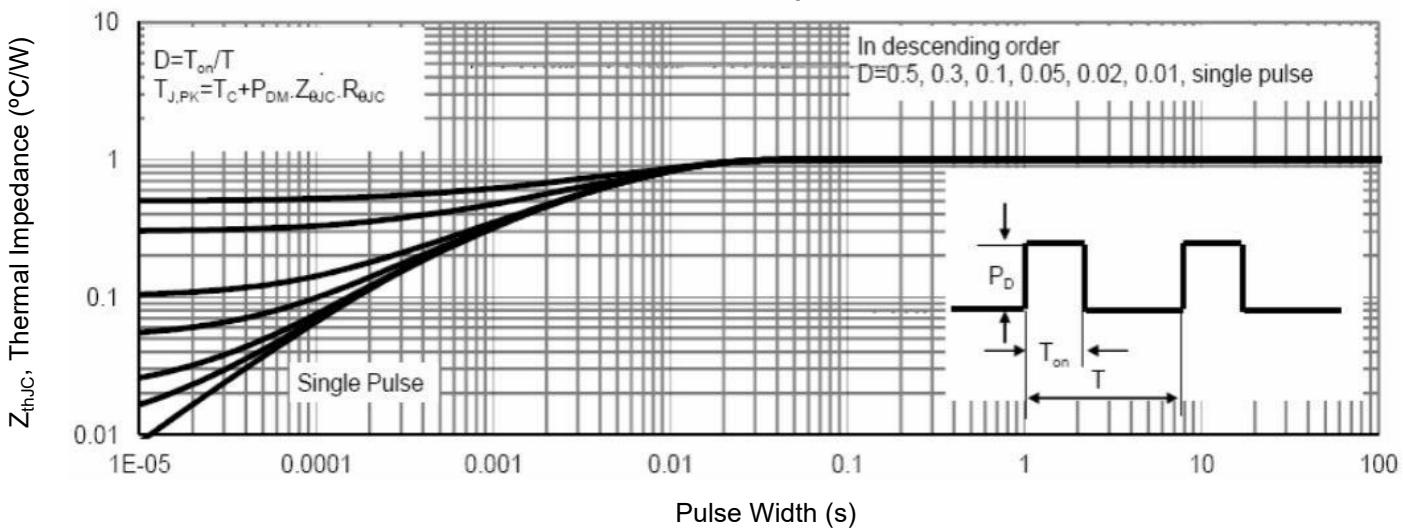
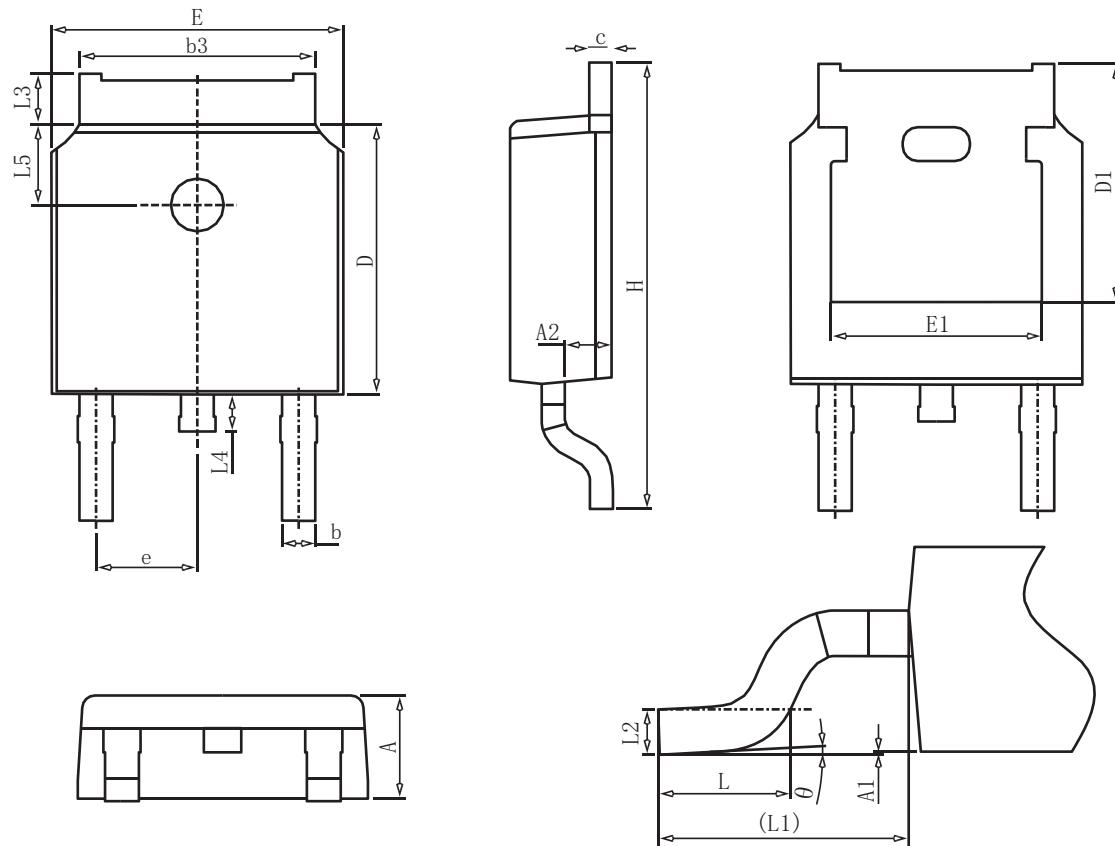


Figure 9. Normalized Maximum Transient Thermal Impedance



TO-252 Package Information



COMMON DIMENSIONS

| SYMBOL | mm | | |
|--------|----------|-------|-------|
| | MIN | NOM | MAX |
| A | 2.20 | 2.30 | 2.40 |
| A1 | 0.00 | - | 0.20 |
| A2 | 0.97 | 1.07 | 1.17 |
| b | 0.68 | 0.78 | 0.90 |
| b3 | 5.20 | 5.33 | 5.50 |
| c | 0.43 | 0.53 | 0.63 |
| D | 5.98 | 6.10 | 6.22 |
| D1 | 5.30REF | | |
| E | 6.40 | 6.60 | 6.80 |
| E1 | 4.63 | - | - |
| e | 2.286BSC | | |
| H | 9.40 | 10.10 | 10.50 |
| L | 1.38 | 1.50 | 1.75 |
| L1 | 2.90REF | | |
| L2 | 0.51BSC | | |
| L3 | 0.88 | - | 1.28 |
| L4 | 0.50 | - | 1.00 |
| L5 | 1.65 | 1.80 | 1.95 |
| θ | 0° | - | 8° |